

L Number	Hits	Search Text	DB	Time stamp
-	50	257/778 and chip and ball and encapsulate and ((conductive adj layer) or (conductive adj ring))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/21 18:07
-	21	257/779 and chip and ball and encapsulate and ((conductive adj layer) or (conductive adj ring))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/27 07:24
-	18	257/780 and chip and ball and encapsulate and ((conductive adj layer) or (conductive adj ring))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/26 17:25
-	29	257/784 and chip and ball and encapsulate and ((conductive adj layer) or (conductive adj ring))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/26 17:28
-	32	257/787 and chip and ball and encapsulate and ((conductive adj layer) or (conductive adj ring))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/26 17:53
-	241	257/778 and chip and (ball or bump) and (electrode adj pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/27 08:14
-	77	257/779 and chip and (ball or bump) and (electrode adj pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/27 08:49
-	140	257/780 and chip and (ball or bump) and (electrode adj pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/27 09:54
-	62	257/781 and chip and (ball or bump) and (electrode adj pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/27 09:16
-	102	257/786 and chip and (ball or bump) and (electrode adj pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/27 09:22
-	131	257/787 and chip and (ball or bump) and (electrode adj pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/27 09:28
-	235	257/737 and chip and (ball or bump) and (electrode adj pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/27 09:39
-	187	257/738 and chip and (ball or bump) and (electrode adj pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/27 09:45
-	36	257/697 and chip and (ball or bump) and (electrode adj pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/27 09:45

-	1441	257/780	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2003/01/27 09:55
-	1998	257/698	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2003/07/21 15:53
-	24	"5741729"	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2003/07/26 12:20
-	22	"5498901"	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2003/07/21 16:29
-	24	"5825628"	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2003/07/21 16:44
-	23	"5903050"	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2003/07/21 16:47
-	31	"5677575"	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2003/07/21 16:47
-	232	257/778 and chip and substrate and ring and ball and wire	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2003/07/22 09:02
-	86	257/779 and chip and substrate and ring and ball and wire	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2003/07/22 09:12
-	111	257/780 and chip and substrate and ring and ball and wire	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2003/07/22 09:38
-	40	257/781 and chip and substrate and ring and ball and wire	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2003/07/22 09:40
-	96	257/784 and chip and substrate and ring and ball and wire	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2003/07/22 11:10
-	121	257/787 and chip and substrate and ring and ball and wire	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2003/07/22 11:46
-	192	257/738 and chip and substrate and ring and ball and wire	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2003/07/26 12:37

-	36	257/680 and chip and substrate and ring and ball and wire	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/22 13:06
-	106	257/690 and chip and substrate and ring and ball and wire	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/22 13:49
-	116	257/692 and chip and substrate and ring and ball and wire	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/22 13:54
-	90	257/693 and chip and substrate and ring and ball and wire	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/22 14:03
-	150	257/698 and chip and substrate and ring and ball and wire	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/22 14:12
-	101	438/108 and chip and substrate and ring and ball and wire	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/22 14:19
-	10	438/116 and chip and substrate and ring and ball and wire	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/22 14:21
-	64	438/612 and chip and substrate and ring and ball and wire	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/22 14:24
-	47	438/614 and chip and substrate and ring and ball and wire	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/22 14:26
-	36	438/617 and chip and substrate and ring and ball and wire	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/26 12:53
-	26	257/.ccls. and (ceramic adj substrate adj insulating)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/27 10:11